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WASHINGTON, D.C. 20231  
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Bib Data Sheet

CONFIRMATION NO. 1120

<b>SERIAL NUMBER</b> 09/687,048	<b>FILING DATE</b> 10/13/2000 <b>RULE</b> 1.47	<b>CLASS</b> 257	<b>GROUP ART UNIT</b> 2811 2814	<b>ATTORNEY DOCKET NO.</b> 45475-00026 99-44650
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**APPLICANTS**

Tae Heon Lee, Kuri-shi, KOREA, REPUBLIC OF;  
Young Suk Chung, Seoul, KOREA, REPUBLIC OF;  
Mu Hwan Seo, Singapore, SINGAPORE;

**\*\* CONTINUING DATA \*\*\*\*\*****\*\* FOREIGN APPLICATIONS \*\*\*\*\***

REPUBLIC OF KOREA 99-44650 10/15/1999

**IF REQUIRED, FOREIGN FILING LICENSE GRANTED**

\*\* 11/22/2000

Foreign Priority claimed 35 USC 119 (a-d) conditions met	<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance	<b>STATE OR COUNTRY</b> KOREA, REPUBLIC OF	<b>SHEETS DRAWING</b> 7	<b>TOTAL CLAIMS</b> 15	<b>INDEPENDENT CLAIMS</b> 4
Verified and Acknowledged	Examiner's Signature _____ Initials _____				

**ADDRESS**

Stanley R. Moore, Esq.  
Jenkins and Gilchrist, P.C.  
3200 Fountain Place  
1445 Ross Ave.  
Dallas, TX 75202

**TITLE**

Leadframe and semiconductor package with improved solder joint strength

<b>FILING FEE RECEIVED</b> 920	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees ( Filing ) <input type="checkbox"/> 1.17 Fees ( Processing Ext. of time ) <input type="checkbox"/> 1.18 Fees ( Issue ) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit
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<b>APPLICANTS</b> Tae Heon Lee, Kuri-shi, KOREA, REPUBLIC OF; Young Suk Chung, Seoul, KOREA, REPUBLIC OF; Mu Hwan Seo, Singapore, SINGAPORE;					
<b>** CONTINUING DATA *****</b>					
<b>** FOREIGN APPLICATIONS *****</b> REPUBLIC OF KOREA 99-44650 10/15/1999					
<b>IF REQUIRED, FOREIGN FILING LICENSE GRANTED</b> <b>** 11/22/2000</b>					
Foreign Priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 (a-d) conditions <input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after met Allowance Verified and Acknowledged _____ Examiner's Signature Initials		<b>STATE OR COUNTRY</b> KOREA, REPUBLIC OF	<b>SHEETS DRAWING</b> 7	<b>TOTAL CLAIMS</b> 15	<b>INDEPENDENT CLAIMS</b> 4
<b>ADDRESS</b> 007663					
<b>TITLE</b> Leadframe and semiconductor package with improved solder joint strength					
<b>FILING FEE RECEIVED</b> 920	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees ( Filing ) <input type="checkbox"/> 1.17 Fees ( Processing Ext. of time ) <input type="checkbox"/> 1.18 Fees ( Issue ) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit		